Zener Diodes Panasonic

## **MAYS0750Z**

### Silicon planar type

For surge absorption circuits

#### ■ Features

- Small terminal capacitance C<sub>t</sub>
- High electrostatic discharge ESD

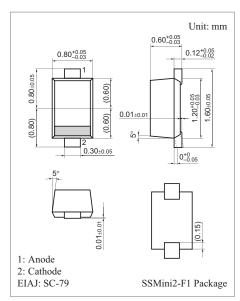
#### ■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit	
Total power dissipation *1	P <sub>T</sub>	150	mW	
Junction temperature	T <sub>j</sub>	150	°C	
Storage temperature	T <sub>stg</sub>	-55 to +150	°C	
Electrostatic discharge *2	ESD	±12	kV	

Note) \*1:  $P_T = 150$  mW achieved with a printed circuit board.

\*2: Test method: IEC61000-4-2

 $(C = 150 \text{ pF}, R = 330 \Omega, \text{ Contact discharge: } 10 \text{ times})$ 



#### Marking Symbol: CZ

### ■ Electrical Characteristics $T_a = 25$ °C±3°C

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Breakdown voltage *	$V_{BR}$	$I_{R'} = 1 \text{ mA}$	6.0	7.5		V
Reverse current	$I_R$	$V_{Rl} = 5 V$			2	μΑ
Terminal capacitance	$C_{t}$	$I_{Rl} = 0 \text{ V}, f = 1 \text{ MHz}$		1.5	3.0	pF

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

<sup>2.</sup> \*:  $V_Z$  guaranted 20 ms after current flow.

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